



PD3S230H

2.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

PowerDI[®]323

Features

- Ultra-Small Surface Mount Package
- Guard Ring Die Construction for Transient Protection
- High Surge Capability
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: PowerDI[®]323
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Polarity: Cathode Band
- Terminals: Finish Matte Tin Annealed Over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (2)
- Weight: 0.006 grams (Approximate)







Bottom View

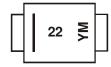
Ordering Information (Note 4)

Part Number	Case	Packaging
PD3S230H-7	PowerDI [®] 323	3000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html.

Marking Information



22 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: B = 2014) M = Month (ex: 9 = September)

Date Code Key

Year	2009	2010	2011	201	12	2013	2014	2015	201	16	2017	2018
Code	W	Х	Υ	Z		Α	В	С	D		Е	F
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings (@T_A = +25°C unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Working Peak Reverse Voltage DC Blocking Voltage	V_{RWM}	30	V
Average Forward Current (See Figure 5)	I _{F(AV)}	2.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30	А

Thermal Characteristics

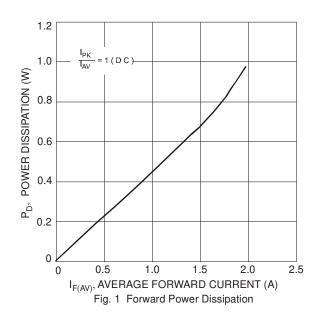
Characteristic	Symbol	Тур	Max	Unit
Thermal Resistance Junction to Soldering Point	$R_{ heta JS}$	_	6	°C/W
Thermal Resistance Junction to Ambient Air (Note 5) @ T _A = +25°C	$R_{ heta JA}$	177	_	°C/W
Thermal Resistance Junction to Ambient Air (Note 6) @ T _A = +25°C	$R_{ heta JA}$	128	_	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +	-150	°C

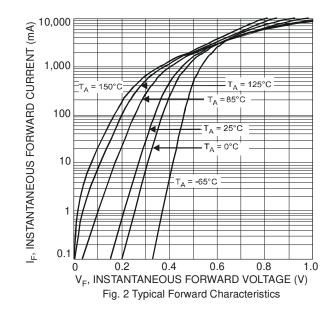
Electrical Characteristics @T_A = +25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	30		_	V	$I_R = 100 \mu A$
Forward Voltage	VF	_		0.60		$I_F = 2.0A$, $T_A = +25$ °C
Toward Voltage	V _F	_	0.50	0.55		$I_F = 2.0A, T_A = +125$ °C
Leakage Current (Note 7)	1_	_	0.7	_		$V_R = 5V, T_A = +25^{\circ}C$
Leakage Guiterii (Note 7)	IR	_	10	100	μΑ	$V_R = 30V, T_A = +25^{\circ}C$
Total Capacitance	C_{T}	_	40	_	pF	$V_R = 10V, f = 1.0MHz$

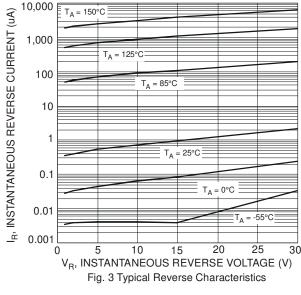
Notes:

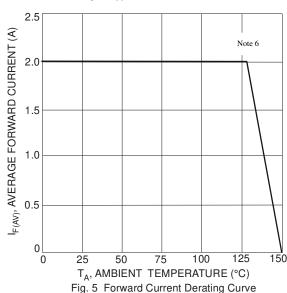
- 5. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf.
- 6. Polymide PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf. 7. Short duration pulse test used to minimize self-heating effect.

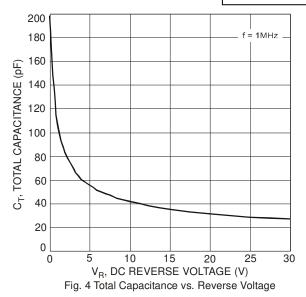


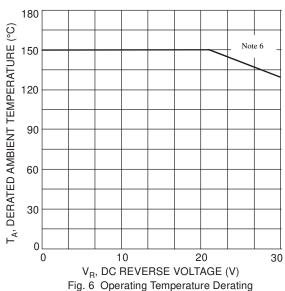






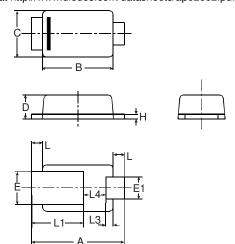






Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

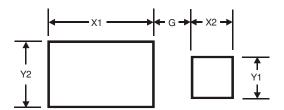


PowerDl [®] 323								
Dim	Min	Max	Тур					
Α	2.40	2.60	2.50					
В	1.85	1.95	1.90					
С	1.20	1.30	1.25					
D	0.60	0.70	0.65					
Е	0.78	0.98	0.88					
E1	0.50	0.70	0.60					
Н	0.08	0.18	0.13					
L	0.20	0.40	0.30					
L1	_	_	1.40					
L3	_	_	0.20					
L4	0.40	0.80	0.60					
All Dimensions in mm								



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
G	0.5
X1	2.0
X2	0.8
Y1	0.8
Y2	1.1

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